

This listing of claims will replace all prior versions, and listings, of claims in the application.

**In the Claims:**

1-18. Canceled.

19. (CURRENTLY AMENDED) A laser machining apparatus comprising:

a workpiece fixture for fastening a workpiece,

a first laser removing device having a first laser source, a first laser beam and a first laser beam outlet for laser drilling a workpiece using first operating parameters, and

a second laser removing device having a second laser source, a second laser beam and a second laser beam outlet ~~which can machine~~ for machining a workpiece using second operating parameters that are different from said first operating parameters,

characterized in that wherein:

the second laser ~~machining apparatus is a laser removing device is~~ configured to for a material removal remove material of the workpiece in layers for the production of a die by material removal in layers,

the first and second laser beam outlets of the ~~[[two]]~~ first and second laser removing devices are fixedly mounted in a manner offset against from each other with respect to at least one axis, ~~[[and]]~~

the first laser removing device comprises one or more of the following operating parameters:

a pulsed laser light having a laser pulse frequency of 0.1 to 100

Hz;

a laser pulse duration of 0.1 to 20 ms;

a pulse peak performance > 1 kW;

a laser performance of 300 W to 3 kW;

an energy per pulse of 1 - 100 J; and

a laser type comprising one of a diode-pumped solid-state laser or a lamp-pumped solid-state laser;

the second laser removing device comprises one or more of the following operating parameters:

a pulsed laser light having a laser pulse frequency of 1 to 100 kHz;

a laser pulse duration of 10 to 1500 ns;

a laser performance of 10 to 200 W;

an energy per pulse of 1 - 50 mJ; and

a laser type comprising a quality-switched solid-state laser; and

~~mechanical adjustment axes are provided by means of which the workpiece may be adjusted translatorily with respect to a machine frame such that it may slide~~ the workpiece fixture is configured to move the workpiece between operating windows of the first and the second laser removal devices.

20. CANCELED.

21. (CURRENTLY AMENDED) The laser machining apparatus according to claims claim 19 [[or 20]],

~~characterized in that~~ wherein at least one of said laser removing devices comprises a beam guide.

22. (CURRENTLY AMENDED) The laser machining apparatus according to claim 19, ~~characterized in that~~ wherein at least one of the first and second laser beam outlet of one or both laser removing devices outlets is slidable movable with respect to at least one axis.

23. (CURRENTLY AMENDED) The laser machining apparatus according to claim 22, ~~characterized in that the laser source~~ wherein said first laser removing device comprises a first laser source and said second laser removing device comprises a second laser source, and further wherein at least one of the first and second laser sources is slidable movable in parallel and in sync [[to]] with the at least one of the first and second laser beam outlet outlets.

24. (CURRENTLY AMENDED) The laser machining apparatus according to claim 19, ~~characterized by~~ further comprising a first control for controlling the first laser removing device and a second control for controlling the second laser removing device.

25. (CURRENTLY AMENDED) The laser machining apparatus according to claim 24, ~~characterized in that~~ wherein the second control operates at a higher clock frequency than the first control.

26. (CURRENTLY AMENDED) The laser machining apparatus according to claims 24 or 25, ~~characterized by~~ further comprising an interface communicating between the first and second controls.

27. (CURRENTLY AMENDED) The laser machining apparatus according to claim 19, ~~characterized in that~~ wherein the first laser removing device comprises a first optical system and the second laser removing device comprises a second optical system.

28. (CURRENTLY AMENDED) The laser machining apparatus according to claim 19, ~~characterized in that~~ wherein the first laser removing device comprises a first sensor system and the second laser removing device comprises a second sensor system.

Application No. 10/595,733  
Amendment Dated 11/18/10  
Reply to Office Action of 6/18/10

29. CANCELED.

30. (CURRENTLY AMENDED) A laser machining method wherein a workpiece is clamped and then machined using laser light, wherein a first ~~operating~~ machining step of laser drilling the workpiece is performed through a first laser removing device having a first laser beam and a first laser outlet and using first operating parameters and a second machining step is performed through a second laser removing device having a second laser beam and a second laser outlet to machine the workpiece using second operating parameters different from the first operating parameters,

characterized in that wherein:

~~the second machining step is the production of a die by material removal in layers using a laser~~ comprises removing material of the workpiece in layers using the second laser beam,

the lasers first and second laser beams of ~~[[both]]~~ the first and second laser removal devices are radiated at the first and second laser beam outlets which are fixedly mounted ~~in a manner~~ offset against from each other with respect to at least one axis, and

~~the workpiece may be adjusted translatorily~~ is moved without changing the clamping ~~with respect to a machine frame using mechanical adjustment axes such that it may be moved~~ between operating windows of the first and the second laser removal devices.

31. (CURRENTLY AMENDED) The method according to claim 30, characterized in that wherein a measurement of the distance necessary for the second machining step is performed before the first machining step is taken.

32. (CURRENTLY AMENDED) The method according to claims 30 or 31, characterized in that wherein during the first machining step using the first laser removing device ~~[[the]]~~ a focusing of the first laser beam is fixed whereas during the second machining step using the second laser removing device ~~[[the]]~~ a focusing of the second laser beam is tracked.

33. (CURRENTLY AMENDED) The method according to claims 30 or 31, characterized in that wherein during the first machining step using the first laser removing device process gas is supplied.

34. (CURRENTLY AMENDED) The method according to claim 32, characterized in that wherein during the first machining step using the first laser removing device process gas is supplied.

35. (CURRENTLY AMENDED) The method according to claim 30, characterized in that wherein during the second machining step using the second laser removing device the location of the second laser beam is guided by a variable beam guide.

36. (CURRENTLY AMENDED) The method according to claim 30, ~~characterized in that~~ wherein during the first machining step using the first laser removing device the relative position of the location of the first laser removing device to the workpiece is changed.

37. (CURRENTLY AMENDED) The method according to claim 30, ~~characterized in that~~ wherein first the machining step having a higher laser performance is taken and then the machining step having a lower laser performance is taken.

38. (CURRENTLY AMENDED) The laser machining apparatus according to claim 19, ~~characterized in that~~ wherein the first and second laser beam outlets of the ~~[[two]]~~ first and second laser removing devices are fixedly mounted ~~in a manner~~ offset from each other with respect to two axes.

39. (CURRENTLY AMENDED) The laser machining apparatus according to claim ~~[[29]]~~ 19, ~~characterized in that~~ wherein the first laser moving device comprises a pulsed laser light having a laser pulse frequency of 1 to 30 Hz.



40. (CURRENTLY AMENDED) The laser machining apparatus according to claim [[29]] 19, characterized in that wherein the first laser moving device has a laser pulse duration of 0.3 to 2 ms.

41. (CURRENTLY AMENDED) The laser machining apparatus according to claim [[29]] 19, characterized in that wherein the first laser moving device has a pulse peak performance greater than 20 kW.

42. (CURRENTLY AMENDED) The laser machining apparatus according to claim [[29]] 19, characterized in that wherein the first laser moving device has an energy per pulse of 10 to 50 J.

43. (CURRENTLY AMENDED) The laser machining apparatus according to claim [[29]] 19, characterized in that wherein the second laser moving device comprises a pulsed laser light having a laser pulse frequency of 10 to 50 kHz.

44. (CURRENTLY AMENDED) The laser machining apparatus according to claim [[29]] 19, characterized in that wherein the second laser moving device has a laser pulse duration of 100 to 500 ns.

45. (CURRENTLY AMENDED) The laser machining apparatus according to claim [[29]] 19, ~~characterized in that~~ wherein the second laser moving device has a laser performance of 20 to 50 W.

46. (CURRENTLY AMENDED) A method according to claim 30, ~~characterized in that~~ wherein the lasers first and second laser beams of [[both]] the first and second laser removal devices are radiated at the first and second laser beam outlets which are fixedly mounted ~~in a manner~~ offset against from each other with respect to two axes.